

International Application No.: PCT/JP2004/017173
U.S. Patent Application No.: Unknown
April 15, 2005
Page 3 of 10

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

ABSTRACT OF THE DISCLOSURE

A laminated ceramic electronic component includes a plurality of conductor pattern layers (2, 3, and 4) for a coil ~~overlaps~~arranged to overlap each other to form substantially U-shaped conductors (2A, 3A, and 4A) for the coil. The conductors ~~(2A, 3A, and 4A)~~ for the coil are electrically connected in series ~~with~~through via holes ~~(15)~~ for interinner layer connection provided in ceramic green sheets ~~(10 and 11)~~ to form a spiral coil-(L). A plurality of leading conductor pattern layers (5 and 6) also overlaps each other to form leading conductors (5A and 6A). One leading conductor pattern layer (5) is disposed per a predetermined number of conductor pattern layers (2) for the coil. An end ~~(51)~~ of each leading conductor pattern layer (5) is in contact with the corresponding conductor pattern layer ~~(2)~~ for the coil. In other words, the thickness of the leading conductors (5A and 6A) is smallerless than the thickness of the conductors ~~(2A to 4A)~~ for the coil.